ATTACHMENT FOR SPECIFICATION AMENDMENTS

The following is a marked up version of each replacement paragraph and/or section of the specification in which underlines indicate insertions and brackets indicate deletions.

[0007] In an aspect of the invention, the frame includes flanges that extend over a top surface of the substrate and that are affixed to at least one of the top surface of the substrate and an outer [edge] perimeter of a lid of the integrated circuit package.

[0008] In an aspect of the invention, the frame is affixed to at least one of an outer [edge] perimeter of the substrate and the outer [edge] perimeter of the lid.

[0009] In an alternative aspect of the invention, support legs support the substrate and have a flange that is affixed to at least one of the top surface of the substrate and an outer [edge] perimeter of the lid of the integrated circuit package.

ATTACHMENT FOR CLAIM AMENDMENTS

The following is a marked up version of each amended claim in which underlines indicate insertions and brackets indicate deletions.

3. (Amended) The apparatus of claim 2 wherein the integrated circuit package has a lid affixed to the substrate, the lid having an outer perimeter that is smaller than an outer perimeter of the substrate, each support member having a flange extending over the upper surface of the substrate, the flange of each support member affixed to at least one of the outer [edges] perimeter of the lid and the upper surface of the substrate by adhesive.

5. (Amended) The apparatus of claim 4 wherein the frame is rectangular and has a support leg and an inwardly extending flange at each corner, each support leg having first and second segments approximately at right angles to each other and each flange having first and second segments at approximately right angles to each other, each flange secured to at least one of the outer [edge] perimeter of the lid and the upper surface of the substrate by adhesive.

6. (Amended) The apparatus of claim [7] 5 wherein the flanges are secured to both the outer [edge] perimeter of the package lid and the upper surface of the substrate by adhesive.

8. (Amended) The apparatus of claim 2 wherein the support member comprises a frame surrounding the integrated circuit package with an inner side of the frame affixed by adhesive to at least one of an outer side of the substrate and an outer [edge] perimeter of a lid affixed to the substrate, the adhesive accommodating any variation in height of the integrated circuit package.

10. (Amended) The apparatus of claim 9, wherein the integrated circuit package has a lid affixed to the substrate, the lid having an outer perimeter that is smaller than an outer perimeter of the substrate, each support leg having a flange extending over an upper surface of the substrate, each flange affixed to at least one of an outer [edge] perimeter of the lid and the upper surface of the substrate by adhesive, the adhesive accommodating any variation in height of the integrated circuit package.

12. (Amended) The apparatus of claim 11, wherein each support leg is affixed to at least one of an outer [edge] perimeter of a lid affixed to the

substrate and an outer [edge] perimeter of the substrate by adhesive, the adhesive accommodating any variation in height of the integrated circuit package.

13. (Amended) The apparatus of claim 10 wherein the integrated circuit package is a column [gird] grid array integrated circuit package.

14. (Amended) A circuit board assembly, comprising:

a. a circuit board;

b. a column grid array integrated circuit package having a substrate with an array of solder columns extending from a bottom surface of the substrate to the circuit board when the column grid array integrated circuit package is mounted on the circuit board, the column grid array integrated circuit package having a lid affixed to the substrate, the lid having an outer perimeter that is smaller than an outer perimeter of the substrate; and

c. at least one support member affixed to at least one of an [edge] outer perimeter of the lid and a top surface of the substrate by adhesive after the column grid array integrated circuit package has been mounted to the circuit board, the adhesive accommodating any variation in height of the column grid array integrated circuit package.

15. (Amended) The apparatus of claim 14, wherein each support member has a flange extending over the upper surface of the substrate, the flange of each support member affixed to at least one of the outer [edge] perimeter of the lid and the upper surface of the substrate by adhesive.

16. (Amended) The apparatus of claim 15 wherein the column grid array integrated circuit package is rectangular and the support member comprises a rectangular frame extending around the substrate, the frame having a support leg and an inwardly extending flange at each corner, each support leg having first and second segments approximately at right angles to each other and each flange having first and second segments at approximately right angles to each other, each flange secured to at least one of the outer [edge] perimeter of the lid and the upper surface of the substrate by adhesive.

19. (Amended) The method of claim 17 wherein the step of providing the support member includes providing a support member comprising a frame that extends around the substrate and affixing the frame [affixed] to the substrate by adhesive, the adhesive accommodating any variation in height of the integrated circuit package.

21. (Amended) The method of claim 20 wherein the step of providing at least one support member comprises providing at least four support members spaced equidistantly around a [periphery] perimeter of the substrate.